# AN IMPROVED FRAMEWORK OF REGION SEGMENTATION FOR DIAGNOSING THERMAL CONDITION OF ELECTRICAL INSTALLATION BASED ON INFRARED IMAGE ANALYSIS

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by

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### LIST OF ABBREVIATIONS

ASTM American Society for Testing & Materials

AUC Area Under Curve

CTREM Complexity Based Transition Region Extraction Method

DoG Difference of Gaussians

EDISON Edge Detection and Image Segmentation

FN False-Negative

FP False-Positive

FPR False-Positive Rate

F Fault Condition

GT Ground Truth

NETA International Electrical Testing Association

JSEG J measure based SEGmentation

MSER Maximally Stable Extremal Regions

MSE Mean Squared Error

MLP Multilayer Perceptron

NEMA National Electrical Manufacturers Association

NFPA National Fire Protection Association

NF No Fault Condition

RBF Radial Basis Function

RANSAC RANdom SAmple Consensus

SIFT Scale Invariant Feature Transform

SI Segmented Image

SVM Support Vector Machine

TRE Transition Region Extraction

TN True-Negative

TP True-Positive

TPR True-Positive Rate

### LIST OF SYMBOLS

 $\alpha$  Absorption of thermal radiation

 $F(\bullet)$  Activation function

 $T_{amb}$  Ambient temperature

 $\theta_{co}$  Angle of clusters matching

 $T_{mean}$  Average temperature

 $T_{bg}$  Background temperature

 $d_B$  Bhattacharyya histogram distance between target and reference region

 $d_C$  Canberra histogram distance between target and reference region

 $H_B$  Classes of image background

 $H_F$  Classes of image foreground

 $d(\Omega_a, \Omega_b)$  Cluster dissimilarity function

 $\alpha_{ent}$  Coefficient of the maximal entropy

 $w_{ij}^1$ ,  $w_{ik}^2$  Connection weights between the hidden and the output layers

 $P(T_g)$  Cumulative probability

 $T_{cut}$  Dendrogram cutting threshold

 $E_{obj}$  Energy emitted directly from the target object

 $E_{amb}$  Energy reflected from other surrounding objects

 $R_i$  Estimated absolute radius of region

 $d_E$  Euclidean histogram distance between target and reference region

 $H_1$ ,  $H_2$  First and second histogram of a region

 $f_j$ ,  $f_k$  First and the second nearest neighbour

 $n_i$  Frequency of gray level

 $Q_{obj}$  Fuzzy objective function

*i* Gray level of an image

 $k_1,k_2$  Hamadani method's constants

 $I_n$  Image brightness value

 $\mathcal{R}_0$  Initial region clustering

*I*<sub>inv</sub> Inverted image

*K* Kernel function parameter

 $\lambda_1, \lambda_2$  Length of the first and second axis of the ellipse

 $F_{sift}$  List of SIFT descriptors

 $A_{gb}$  Local accumulated gradient of brightness

 $E(\Omega_k)$  Local entropy of neighborhood

 $\hat{x}$  Local extrema

 $T_{coef}$  Local texture coefficient

 $X_{match}$  Matching candidate coordinates

 $T_{match}$  Matching threshold

 $d_M$  Matusita histogram distance between target and reference region

 $Q_i$  Maximally stable region

 $T_{max}$  Maximum temperature of the selected region

 $T_{rmax}$  Maximum temperature range of the image

μ Mean

 $E_r$  Mean squared error

 $\mu_b$  Mean values of the image background

 $\mu_f$  Mean values of the image foreground

 $T_{component}$  Measured absolute temperature of the component

 $T_{rmin}$  Minimum temperature range of the image

S Multiplication factor of the scale-space image

Neurons in the input layer  $v_i$ Number of clusters  $C_l$ Number of hidden nodes  $n_h$ Number of input nodes  $n_i$ Number of samples nNumber of pixels in the neighbourhood of grayscale image  $g_j$ Orientation CPenalty parameter of error (Cost) Pixel intensity value at a certain point in the grayscale image  $T_{gray}$ Predicted output  $d_k$ Probability distribution of the image histogram p(i)Probability distribution local entropy of neighbourhood p(j)RBF kernel function parameter γ  $T_r$ Real temperature value  $T_{ref}$ Reference temperature Reflection of thermal radiation ρ  $DT_{bg}$ Relative to ambient temperature  $S_f$ Scaling factor of the image scale  $T_h$ Segmentation threshold SIFT feature descriptor fSlack variable ζ Small neighbourhood window of image  $Q_k$ Stability criterion of region  $q_R$ Standard deviation of image intensity  $\sigma_{sd}$ Standard deviation of image background  $\sigma_b$ 

 $\sigma_f$  Standard deviation of image foreground

 $y_k$  Target output in the output layer

 $\Delta T_{phase}$  Temperature difference between phases

 $T_{delta}$  Temperature difference between target equipment and reference region

 $T_{kurt}$  Temperature kurtosis

 $T_{\sigma}$  Temperature standard deviation

 $T_{skew}$  Temperature skewness

 $T_{var}$  Temperature variance

 $T_{mgv}$  The highest grayscale value of the image

L The highest pixel intensity in the image

 $T_{LI}$  The hot spot temperature of the measured object

 $T_{L2}$  The hotspot temperature of the reference object

 $b_i$  Threshold in the hidden nodes

 $T_g$  Threshold value to divide the class variance

 $E_{cam}$  Total energy sensed by an infrared camera

 $N_{pixel}$  Total number of image pixels

τ Transmission of thermal radiation

 $E_{bg}$  Transmitted energy through the target object by other surrounding

objects

 $v_p$  Voted cluster pair

*I<sub>h</sub>* Warm region enhancement

*m* Weighting exponent parameter

 $\sigma$  Width of Gaussian filter

 $d_X$   $\chi^2$  histogram distance between target and reference region

 $W_0, W_1$  Zero-order cumulative moment

## SATU RANGKA PENINGKATAN SEGMENTASI RANTAU UNTUK DIAGNOSIS KEADAAN TERMA PEMASANGAN ELEKTRIK BERDASARKAN ANALISIS IMEJ INFRAMERAH

### **ABSTRAK**

Keadaan yang tidak normal bagi peralatan elektrik akan berlaku apabila suhunya melebihi had yang dibenarkan, yang boleh mengakibatkan kegagalan peralatan tersebut. Oleh itu, pencegahan awal amat penting untuk mengelakkan perkara ini berlaku disamping meningkatkan kebolehpercayaan peralatan tersebut. Kajian ini mencadangkan satu teknik baharu bagi segmentasi kawasan imej dan kaedah untuk mendiagnosis keadaan haba bagi peralatan elektrik dengan mengambilkira analisa imej inframerah secara kualitatif dan kuantitatif. Memandangkan kebanyakan pemasangan elektrik kebiasaannya disusun secara tetap dengan struktur yang berulang-ulang, satu kaedah baharu dicadangkan bagi mengesan semua struktur peranti elektrik yang serupa dalam satu imej inframerah. Kaedah ini menggunakan gabungan dua algoritma pengesan titik utama iaitu algoritma transformasi ciri-ciri invarian skala (SIFT) dan kawasan ekstrem yang stabil (MSER) bagi meningkatkan bilangan pengesanan titik utama. Satu kaedah baharu untuk memadan dan menterjemahkan kluster telah dicadangkan dengan memperkenalkan prosedur pengundian bagi menentukan padanan kluster. Pengesanan rantau dicapai dengan menggunakan kaedah grid di mana ia membahagikan kelompok-kelompok berulang sebelum keseluruhan objek yang disasarkan itu disegmentasi dengan sempurna. Untuk menilai keadaan pemasangan peralatan elektrik, keberkesanan menggunakan tiga jenis ciri input yang berbeza telah diselidiki. Pendekatan model 'wrapper' digunakan untuk memilih ciri yang sesuai di mana perseptron berbilang

lapisan (MLP) rangkaian neural tiruan dan mesin vektor sokongan (SVM) digunakan untuk menilai setiap set gabungan ciri. Berdasarkan hasil kajian terhadap kaedah segmentasi yang dicadangkan, kira-kira 94.27% dari rantau telah dikesan dengan betul dengan purata nilai kawasan di bawah lengkung (AUC) sebanyak 0.79 telah dicapai. Semasa menentukan keadaan terma, didapati bahawa gabungan ciri input  $T_{delta}$ ,  $T_{skew}$ ,  $T_{kurt}$ ,  $T_{\sigma}$  dan  $d_B$  menghasilkan ketepatan terbaik bagi mengesan kerosakan haba yang diklasifikasikan oleh SVM menggunakan fungsi kernel asas jejarian. Kadar prestasi tertinggi dicapai pada 99.46% dan 97.78% berdasarkan ketepatan dan nilai f-score.